

L Number	Hits	Search Text	DB	Time stamp
1	2	solder with (high adj thermal adj conductivity near2 low adj melt\$3 adj point)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:48
2	4	solder and (high adj thermal adj conductivity near2 low adj melt\$3 adj point)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:03
3	13	high adj thermal adj conductivity near2 low adj melt\$3 adj point	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:03
4	322	solder and (high adj thermal adj conductivity) and (low adj melt\$3 adj point)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:03
5	24	solder and (high adj thermal adj conductivity) with (low adj melt\$3 adj point)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:23
6	356	(metal organic) adj (layer film) near2 surface near2 (cover lid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:25
7	9	(metal organic) adj (layer film) near2 surface near2 lid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:25
-	212	(metal near (layer film)) near2 surface near2 (die chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 14:32
-	123	((metal near (layer film)) near2 surface near2 (die chip)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 14:33
-	65	((((metal near (layer film)) near2 surface near2 (die chip)) and substrate) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 15:25
-	9	("5291064" "5508230" "5895972" "5907189" "5985412" "6118177" "6245249" "6317326" "6390181").PN.	USPAT	2004/10/15 14:59
-	4	("4047198" "4561011" "4612601" "4748538").PN.	USPAT	2004/10/15 15:02
-	3	("4034468" "4034469" "4233645").PN.	USPAT	2004/10/15 15:08
-	83	((metal near (layer film)) near2 surface near2 (die chip)) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:46